

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Beaman et al.

Serial No.: 09/921,867

Filed: August 3, 2001

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

Date: June 11, 2002

Group Art Unit: 3729

Examiner:

Docket No.: YOR919930028US6

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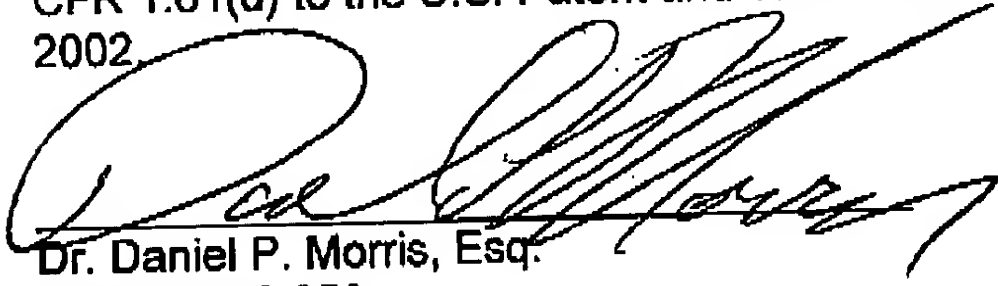
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GROUP 3700

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Washington, D. C. 20231

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Dr. Daniel P. Morris, Esq.
Reg. No. 32,053SIXTH PRELIMINARY AMENDMENT

IN THE CLAIMS

Added claims 251-318.

250
251. (Added) A structure comprising:

a substrate having first and second opposed sides with a first set of contact locations on the first side and a second set of contact locations on the second side;

01 FC:103

1224.00 CH

02 FC:102

420.00 CH